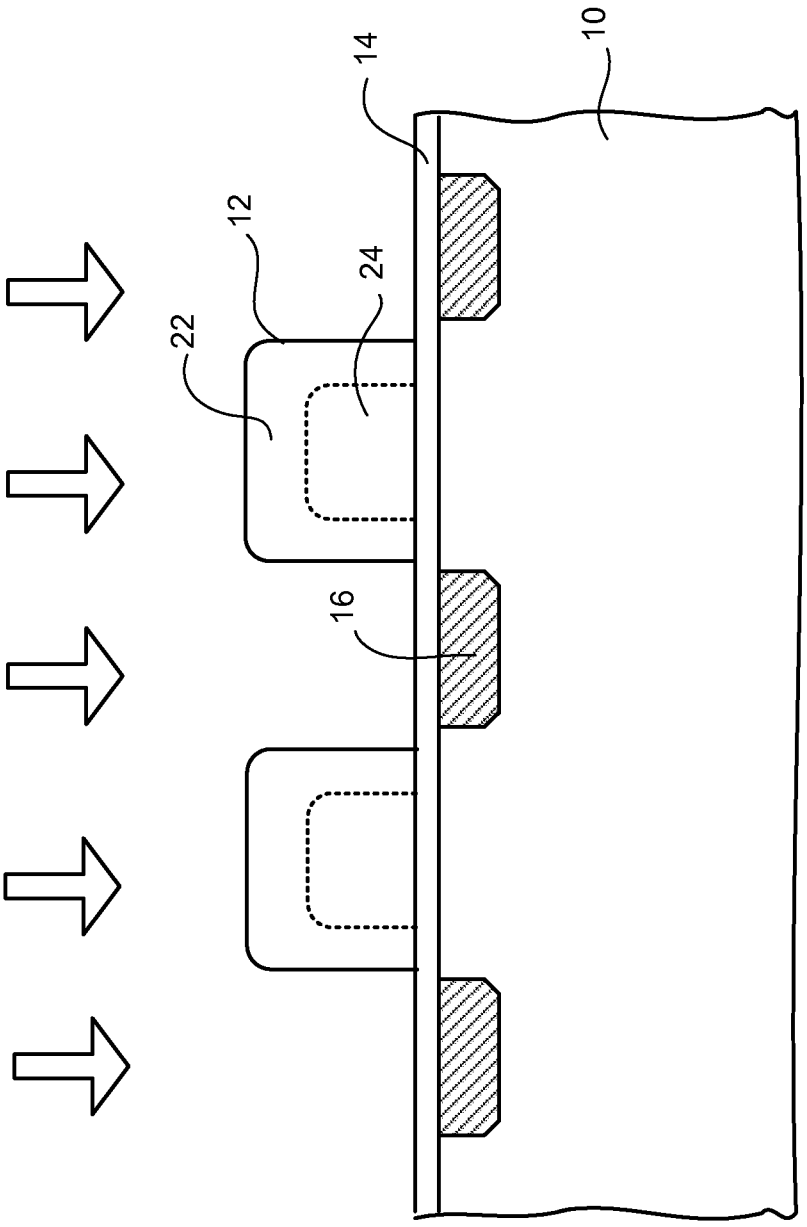


FIG. 1A

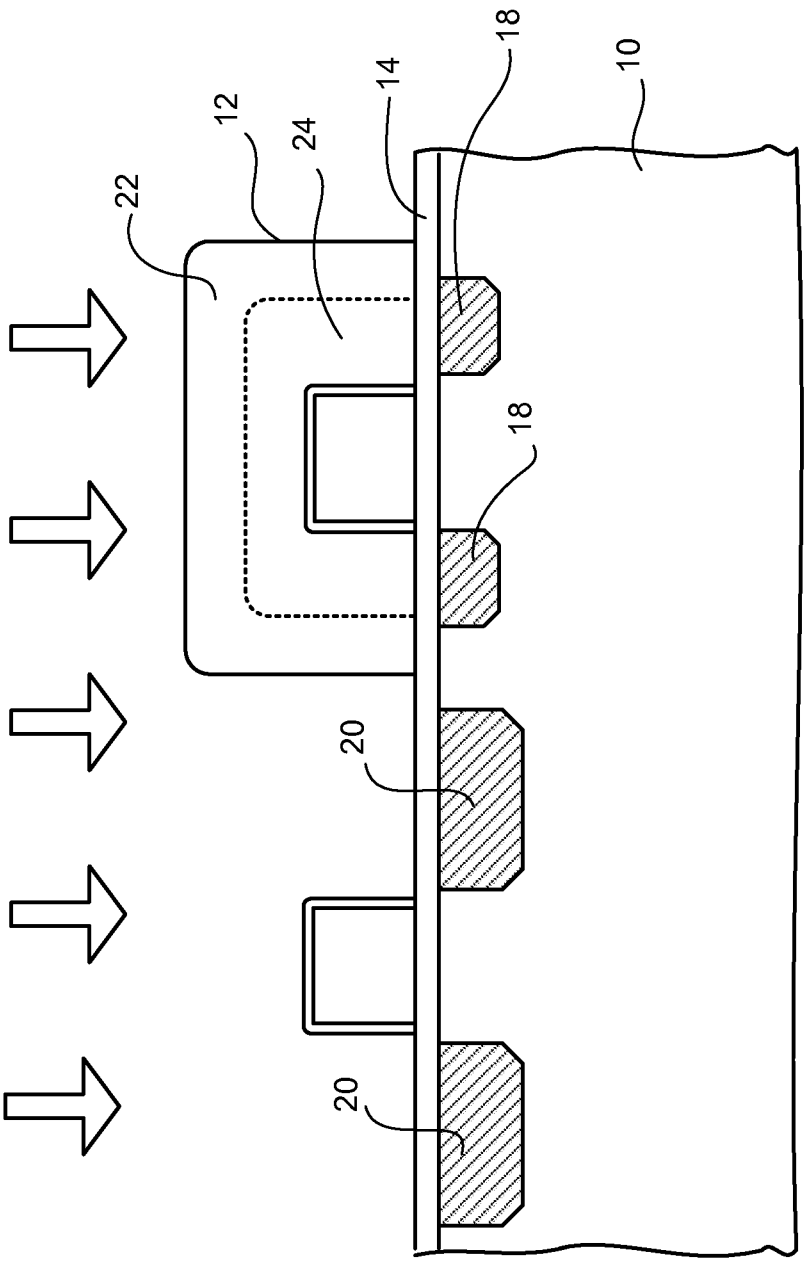


FIG. 1B

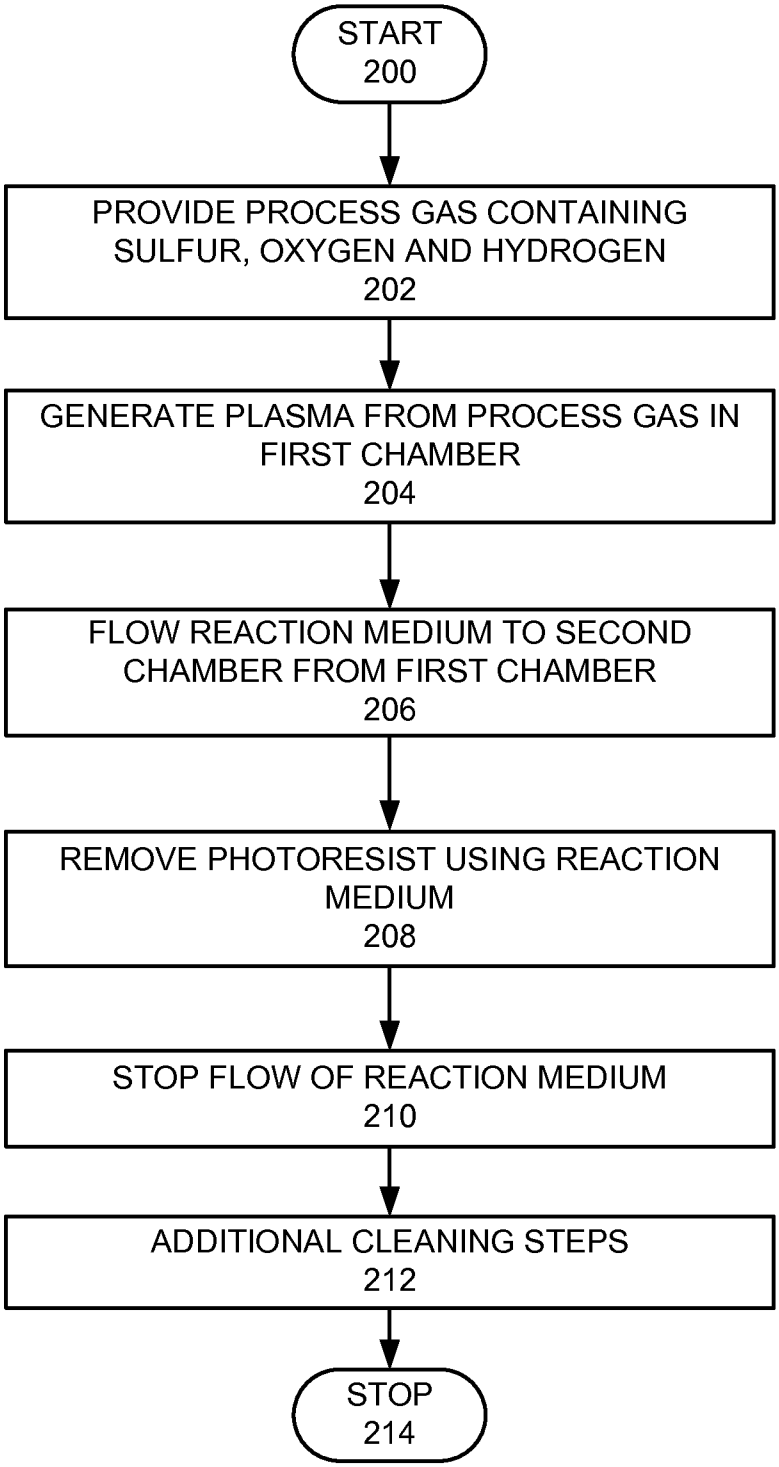

START
200
PROVIDE PROCESS GAS CONTAINING SULFUR, OXYGEN AND HYDROGEN
202
GENERATE PLASMA FROM PROCESS GAS IN FIRST CHAMBER
204
FLOW REACTION MEDIUM TO SECOND CHAMBER FROM FIRST CHAMBER
206
REMOVE PHOTORESIST USING REACTION MEDIUM
208
STOP FLOW OF REACTION MEDIUM
210
ADDITIONAL CLEANING STEPS
212
STOP
214

FIG. 2

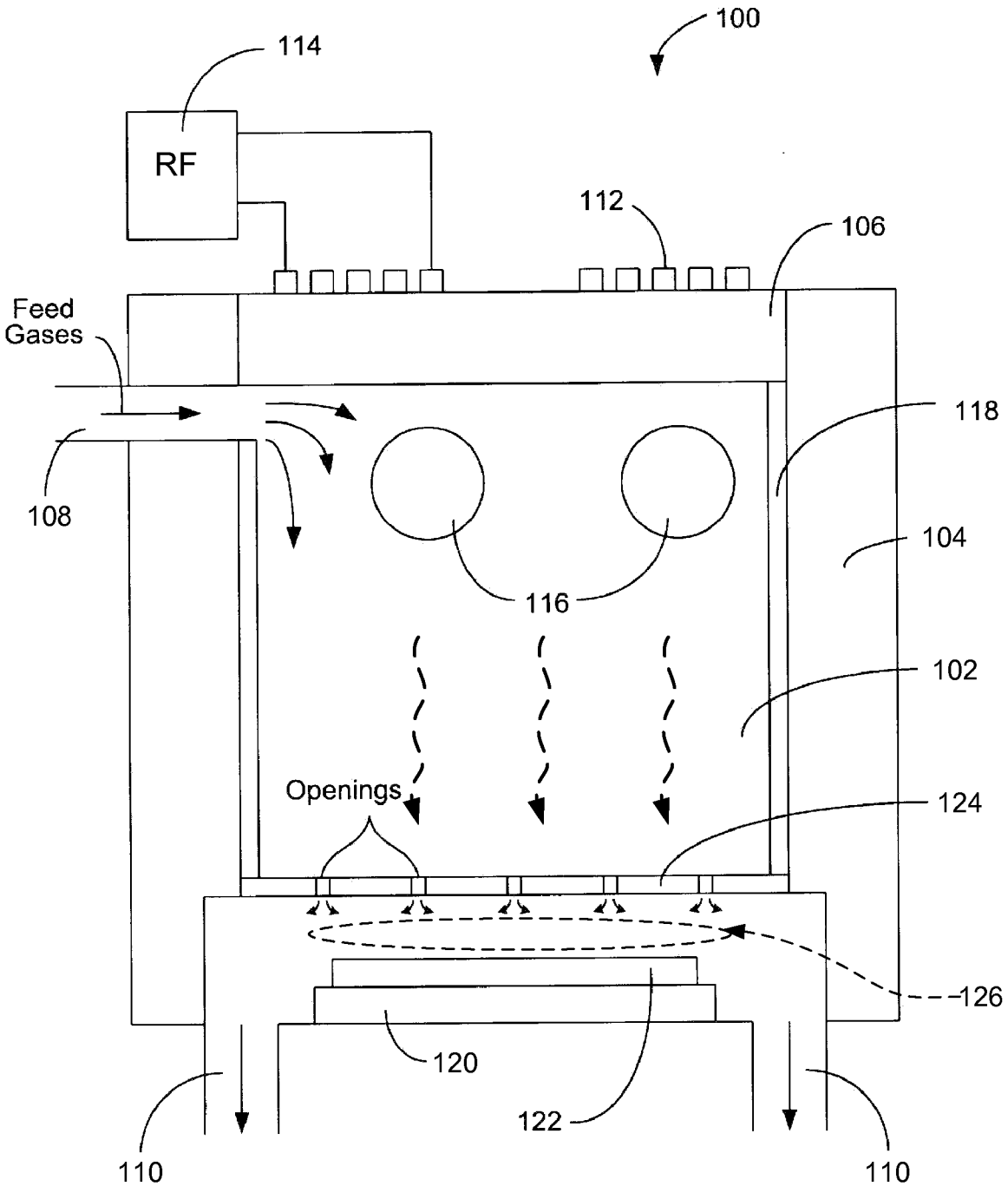

100
114
RF
112
106
Feed
Gases
118
108
104
116
102
Openings
124
126
120
122
110
110

FIG. 3

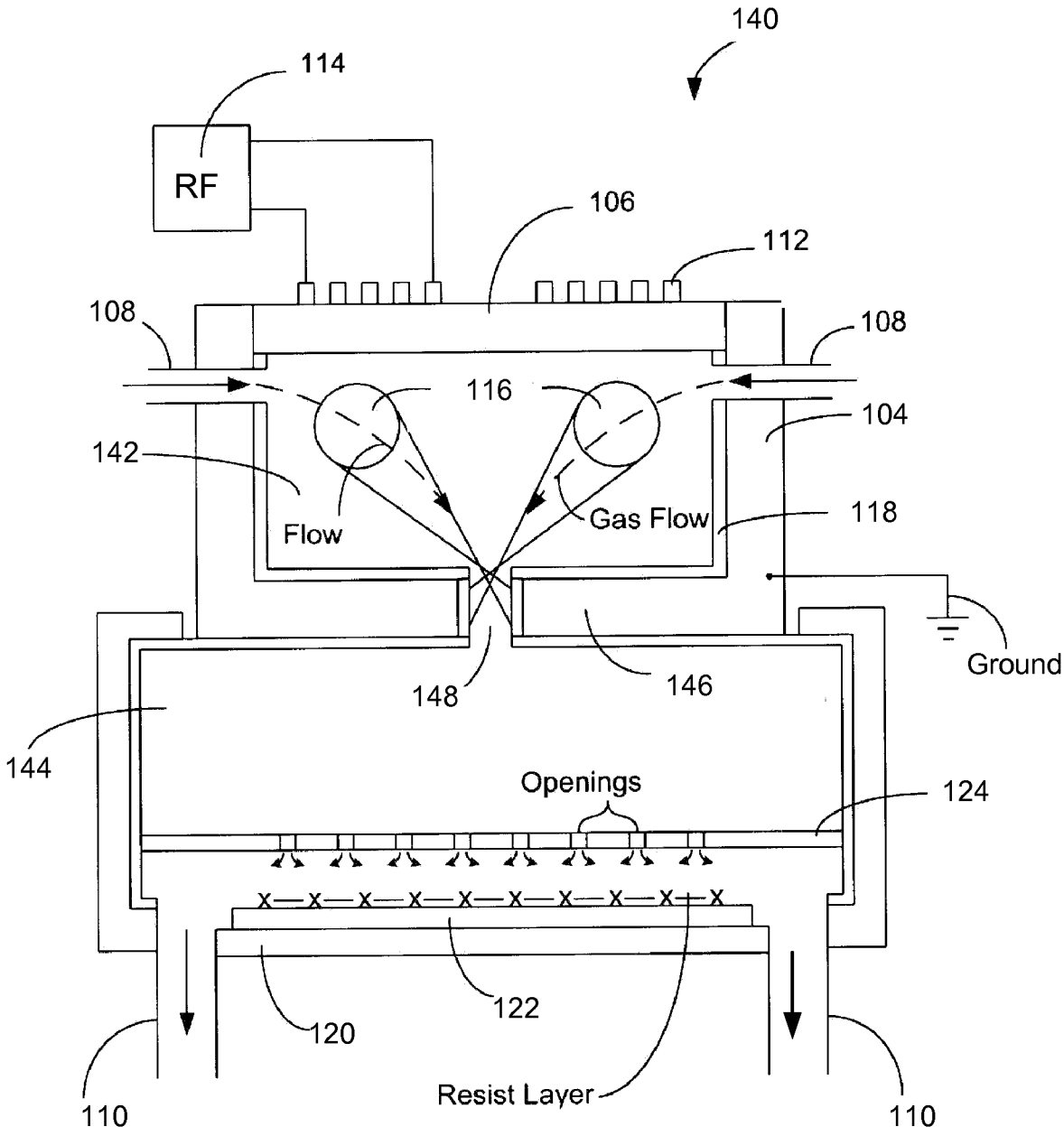

140
114
RF
106
112
108
108
116
104
142
Flow
Gas Flow
118
Ground
148
146
144
Openings
124
120
122
Resist Layer
110
110

FIG. 4A

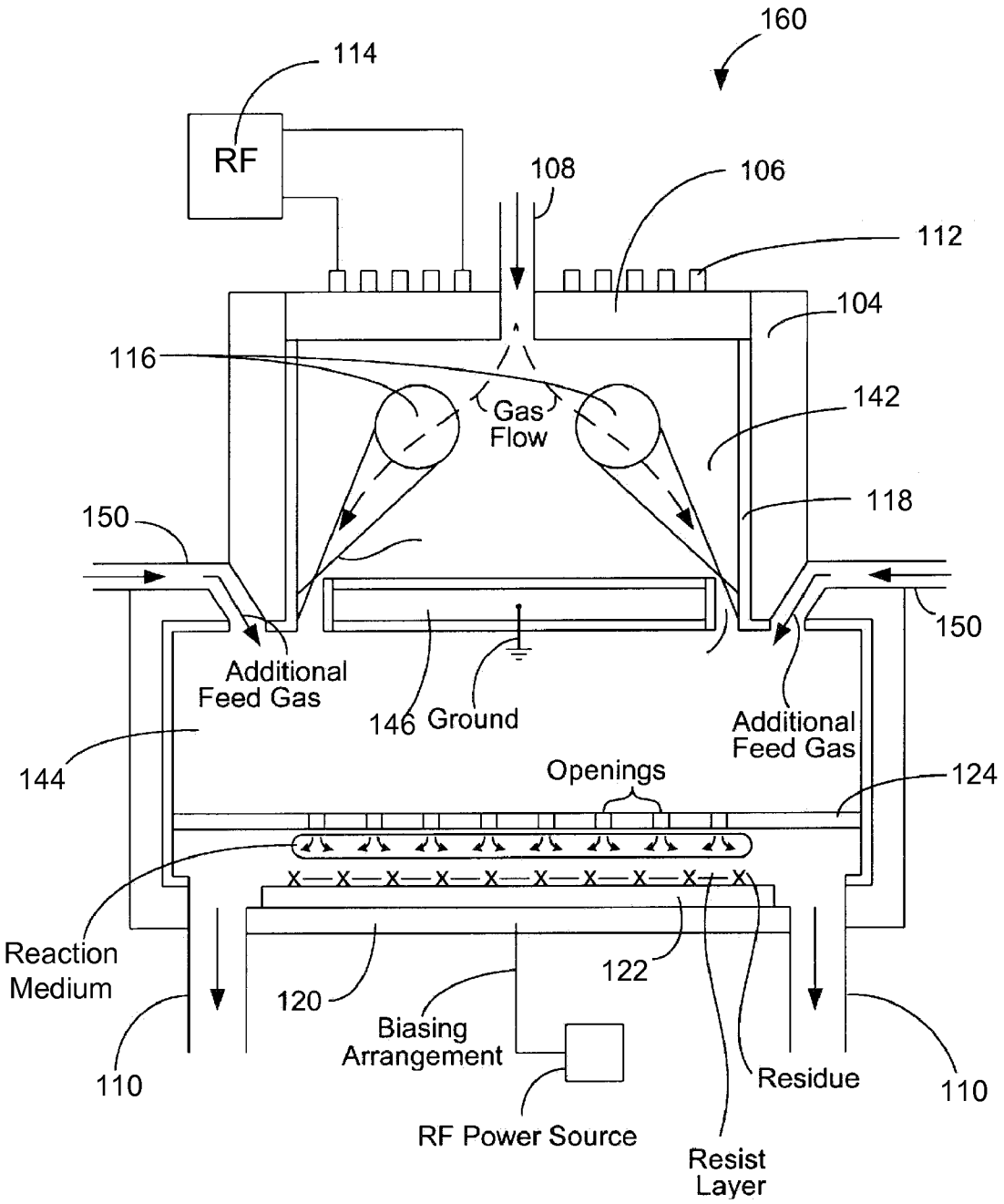

160
114
RF
108
106
112
104
116
Gas
Flow
142
118
150
150
Additional
Feed Gas
146
Ground
Additional
Feed Gas
144
Openings
124
Reaction
Medium
120
122
Biasing
Arrangement
110
Residue
110
RF Power Source
Resist
Layer

FIG. 4B

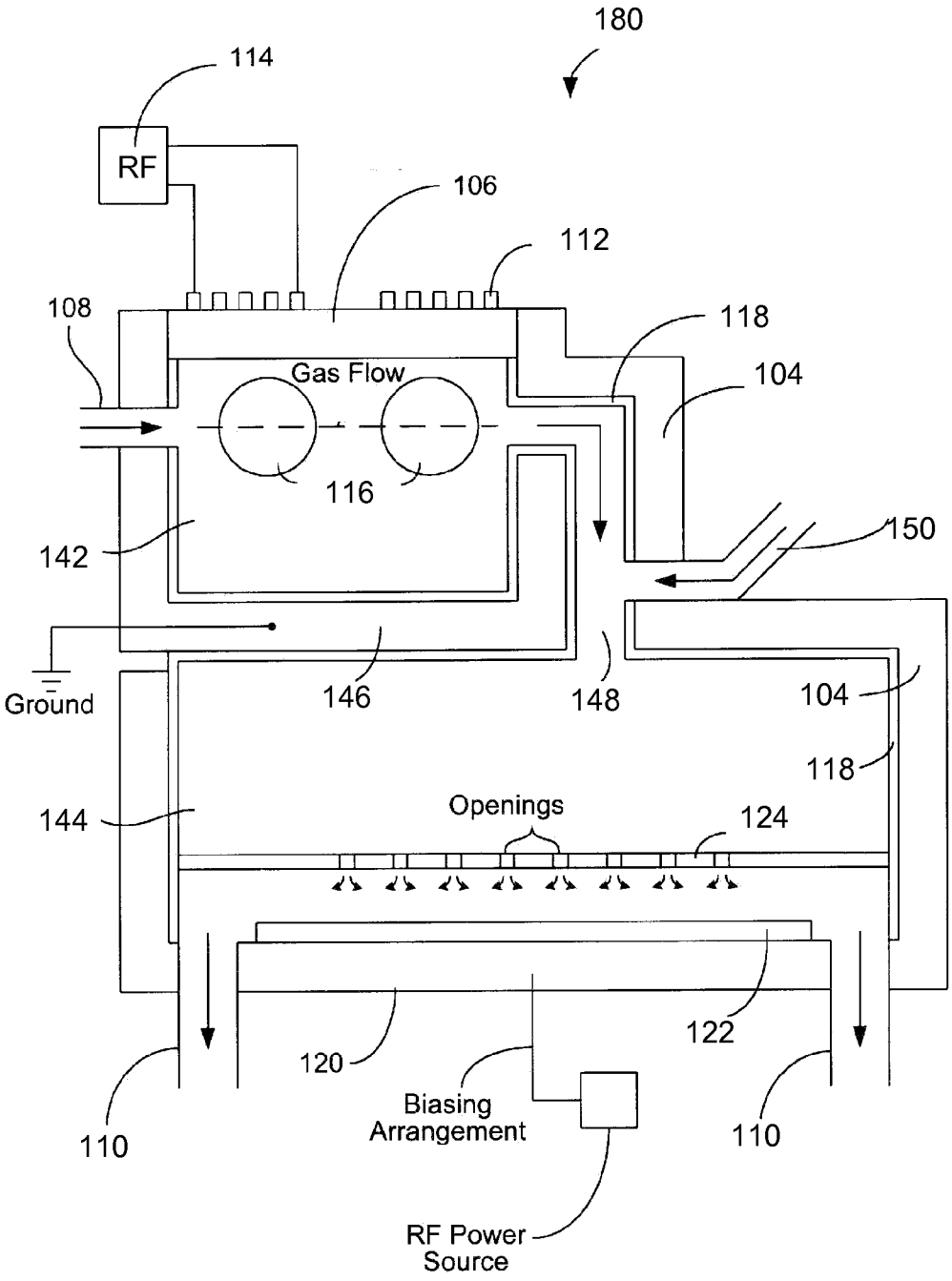

180
114
RF
106
112
108
118
Gas Flow
104
116
142
150
Ground
146
148
104
118
144
Openings
124
120
122
Biasing
Arrangement
110
110
RF Power
Source

FIG. 5

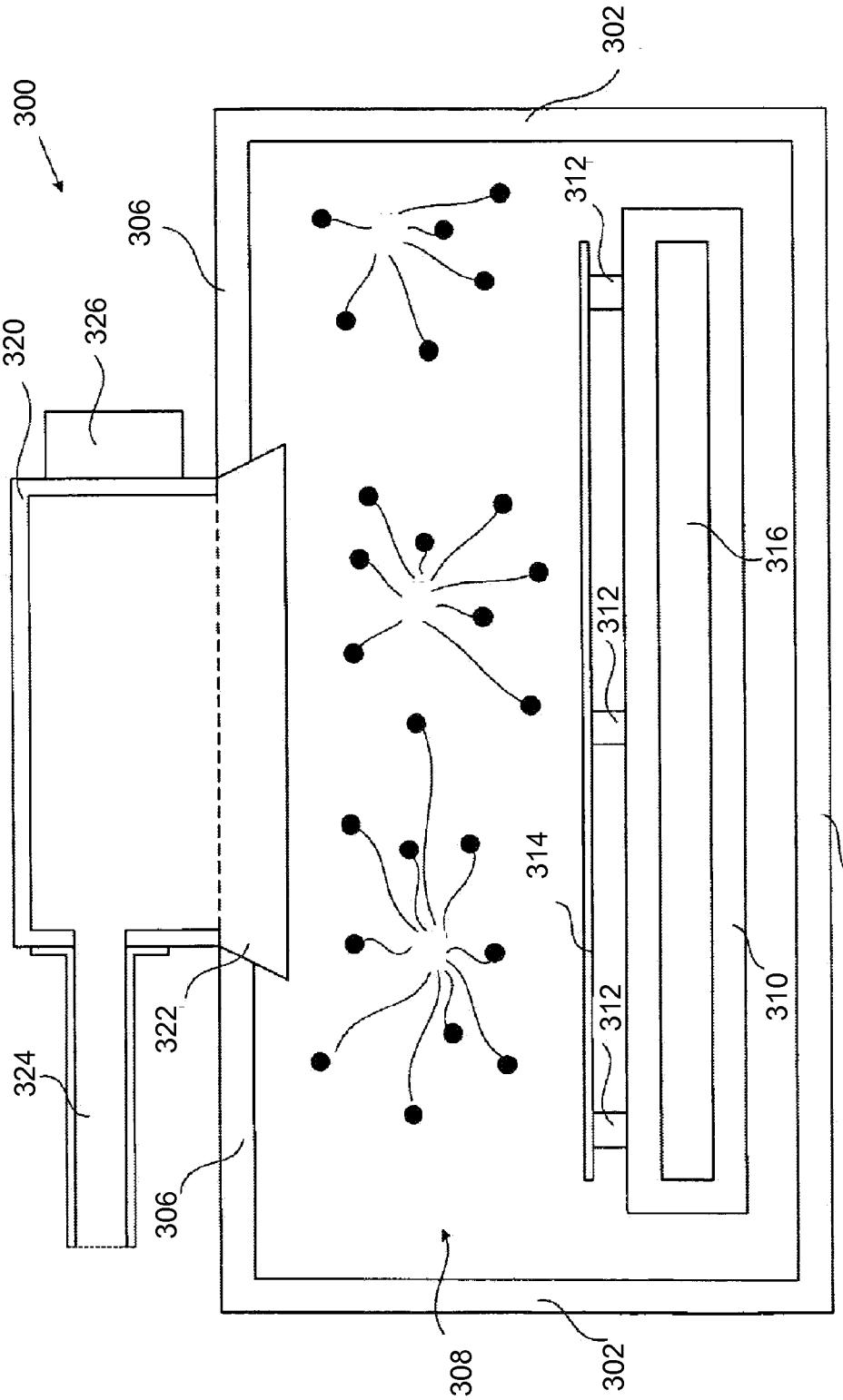

300
302
306
312
326
320
316
312
314
304
312
310
324
322
306
308
302

FIG. 6

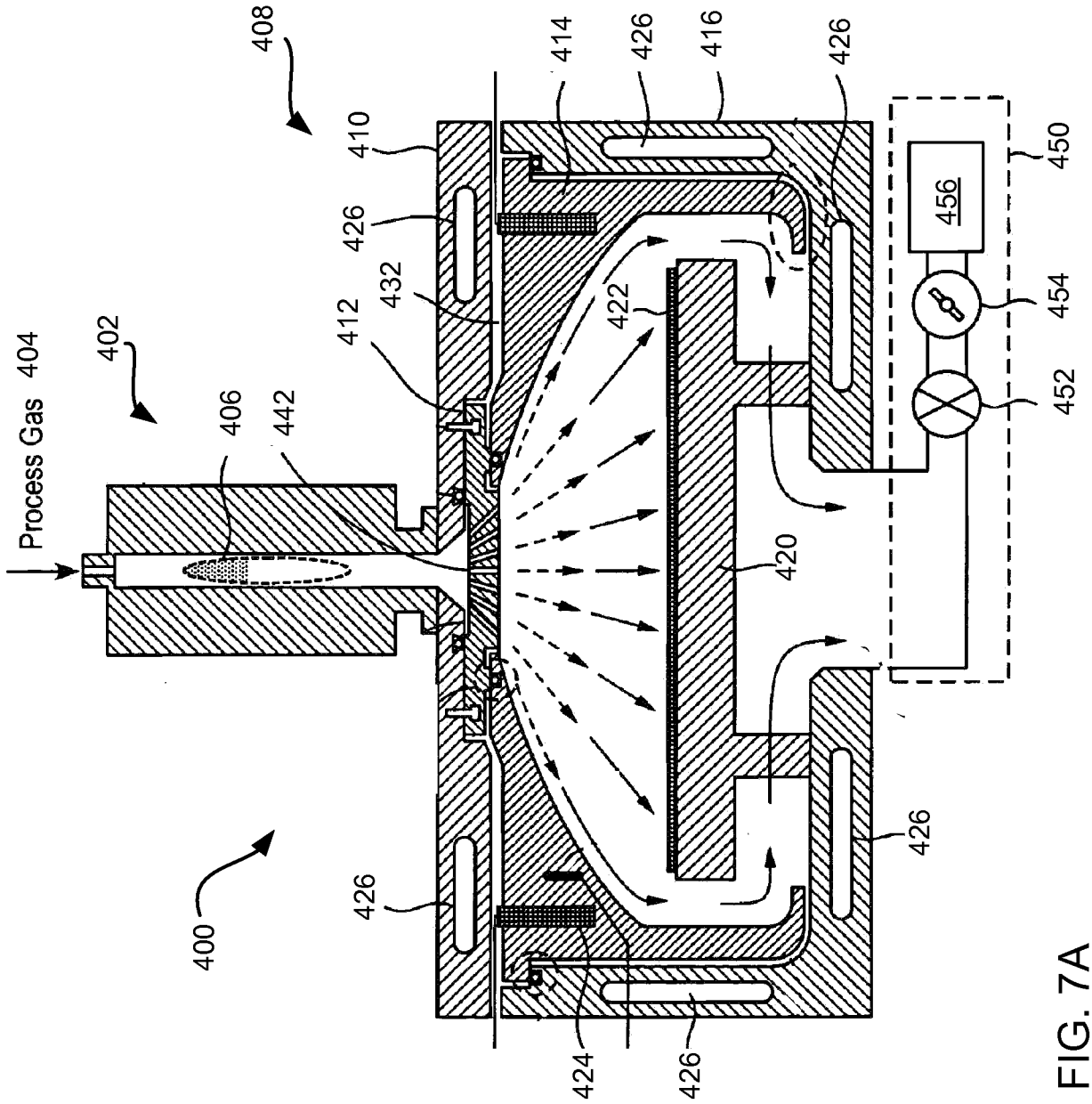

Process Gas
404
402
406
442
408
410
412
432
426
414
426
416
426
422
420
426
426
424
426
400
450
456
454
452

FIG. 7A

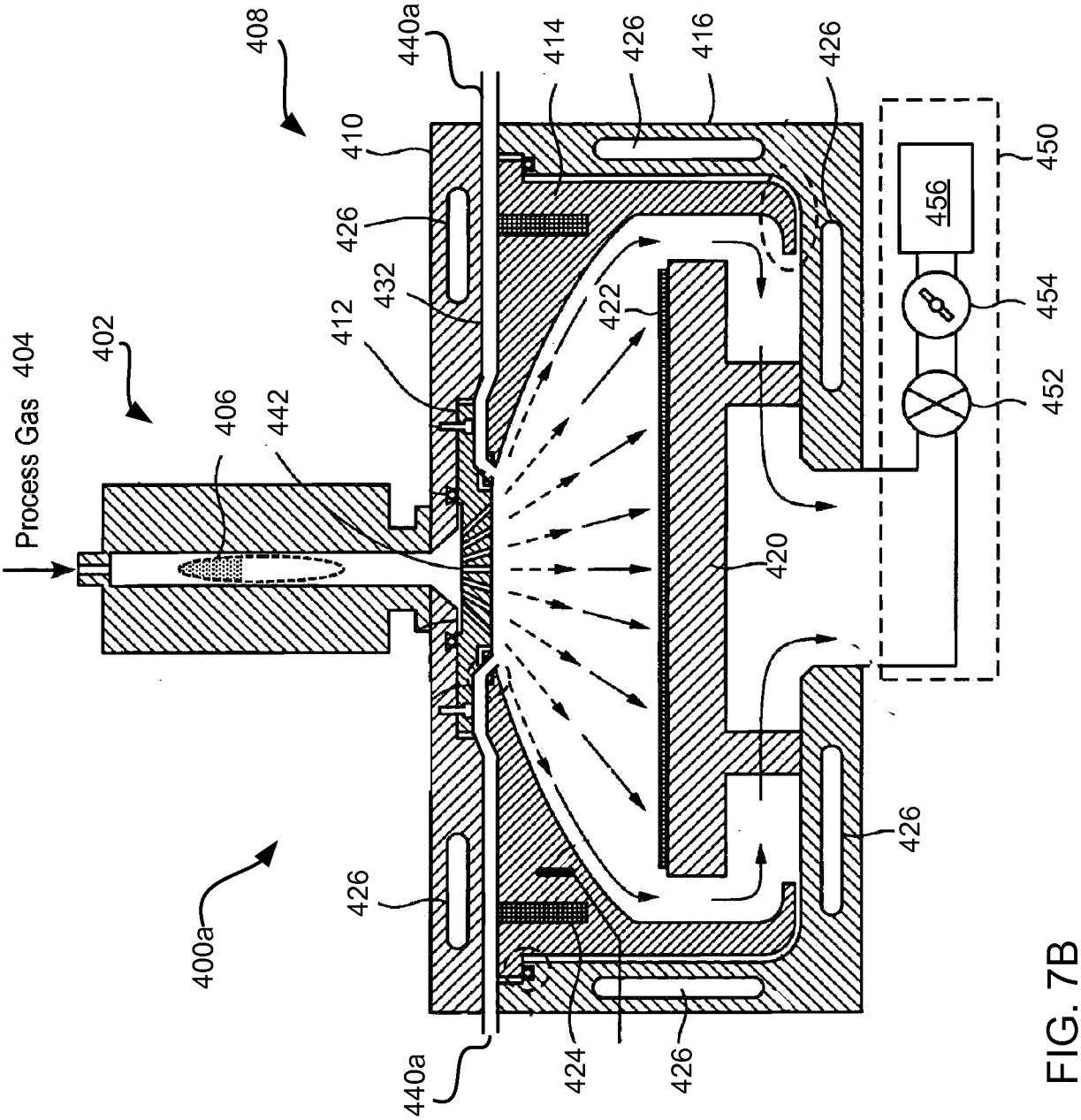

Process Gas 404
402
406
442
408
410
412
432
426
440a
414
426
416
426
422
420
426
426
424
426
440a
400a
450
456
454
452

FIG. 7B

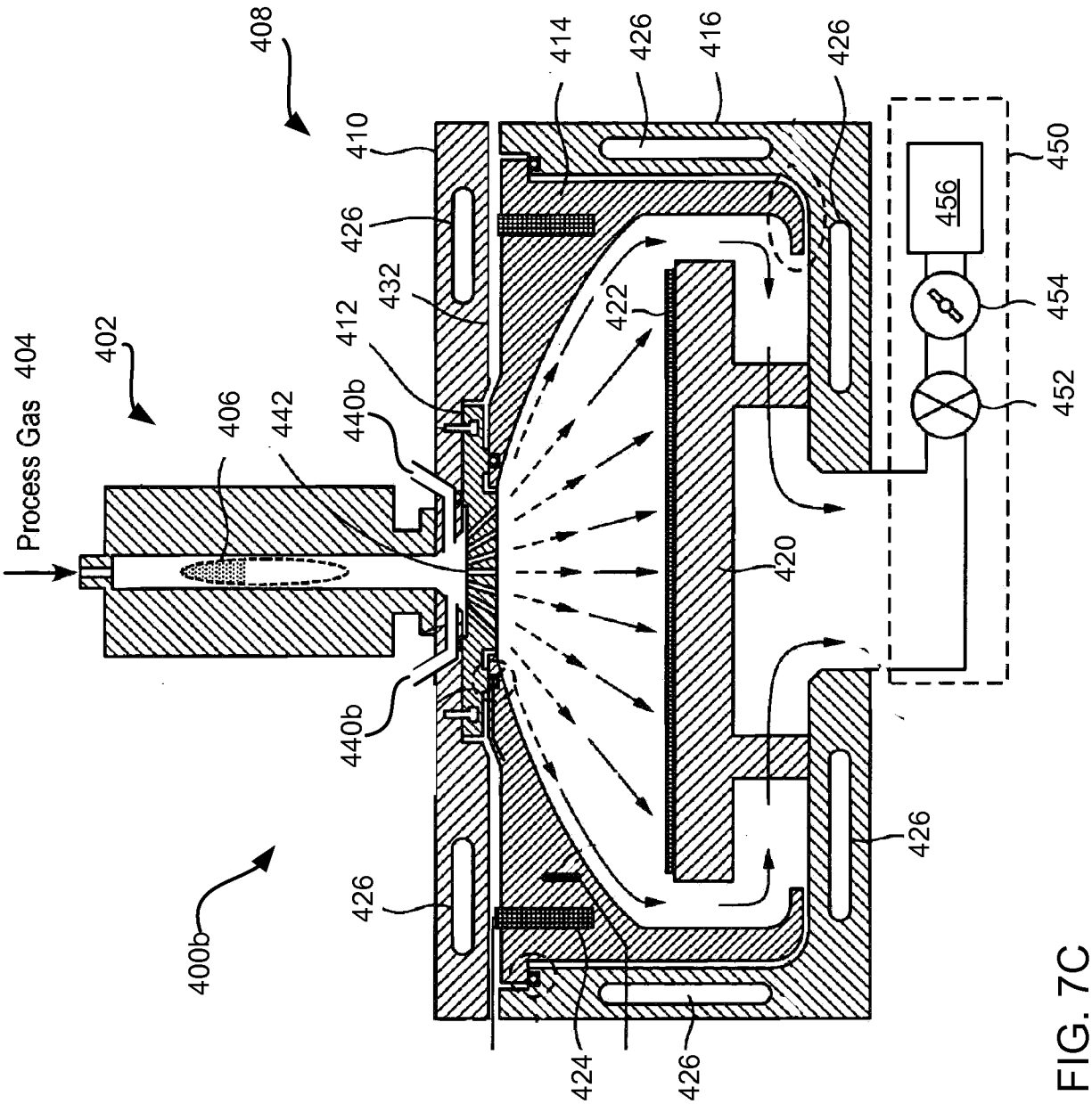

Process Gas
404
402
406
442
440b
412
432
408
410
426
414
426
416
426
422
420
456
450
454
452
440b
426
426
424
426
400b

FIG. 7C

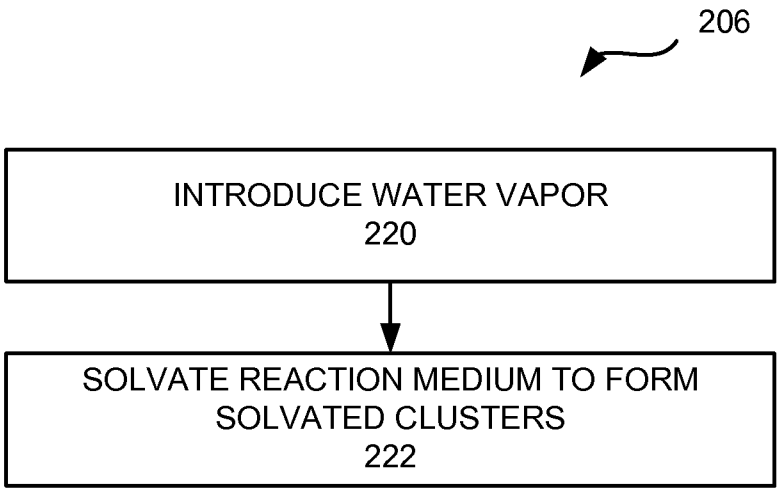

206
INTRODUCE WATER VAPOR
220
SOLVATE REACTION MEDIUM TO FORM SOLVATED CLUSTERS
222

FIG. 8

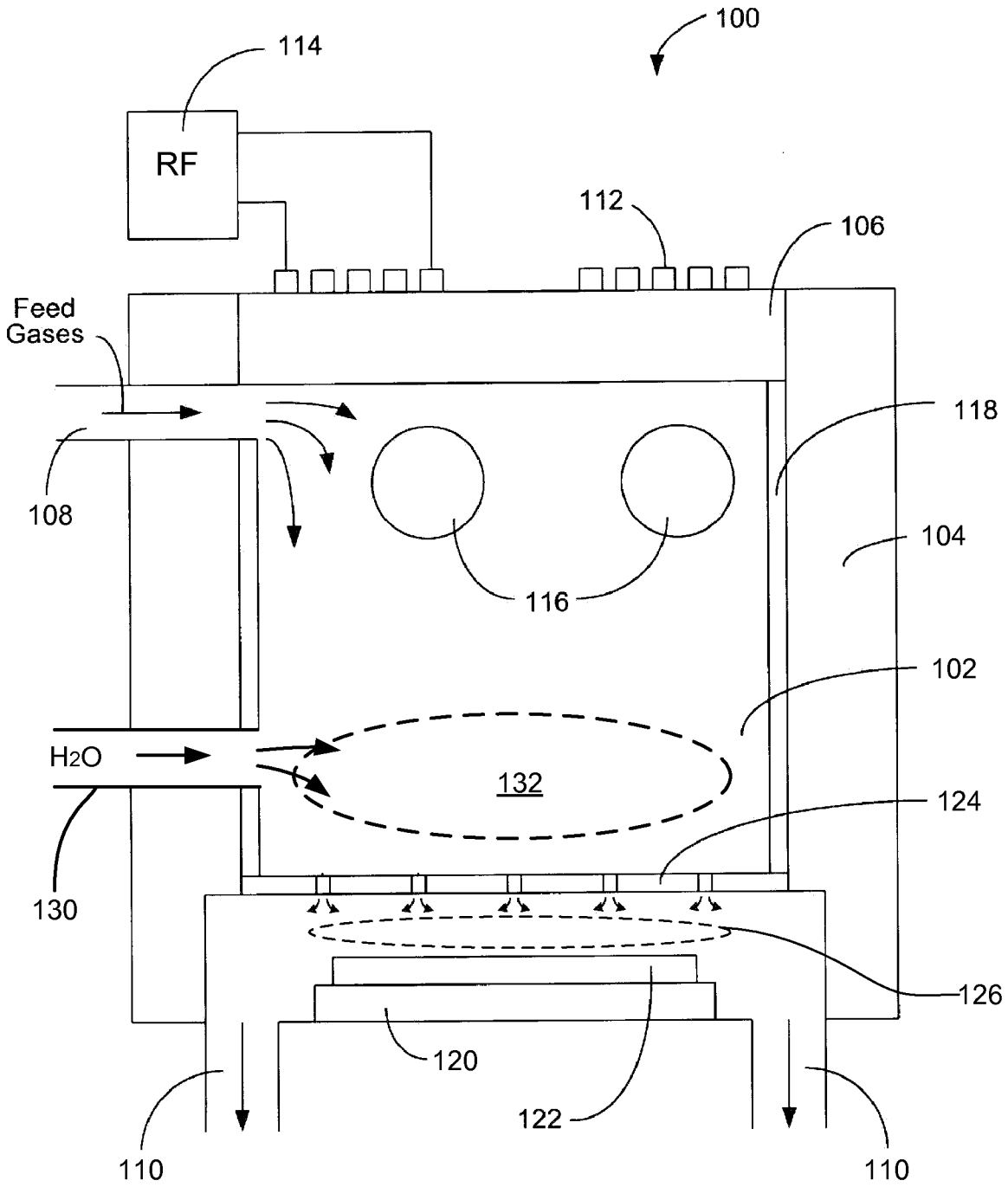

100
114
RF
112
106
Feed
Gases
118
108
104
116
102
H2O
132
124
130
126
120
122
110
110

FIG. 9

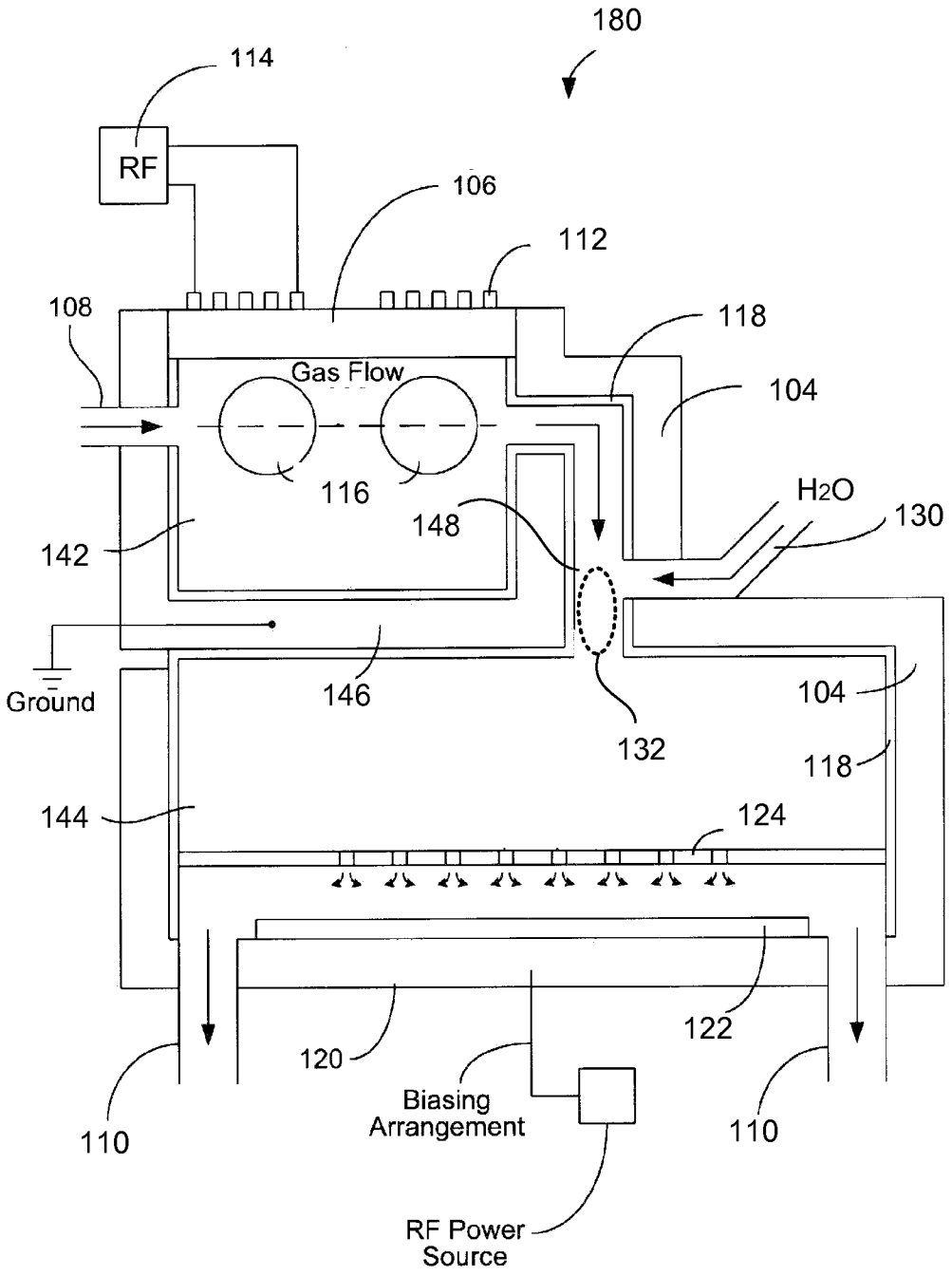

180
114
RF
106
112
108
118
Gas Flow
104
116
148
H2O
130
142
Ground
146
104
132
118
144
124
120
122
Biasing
Arrangement
110
110
RF Power
Source

FIG. 10

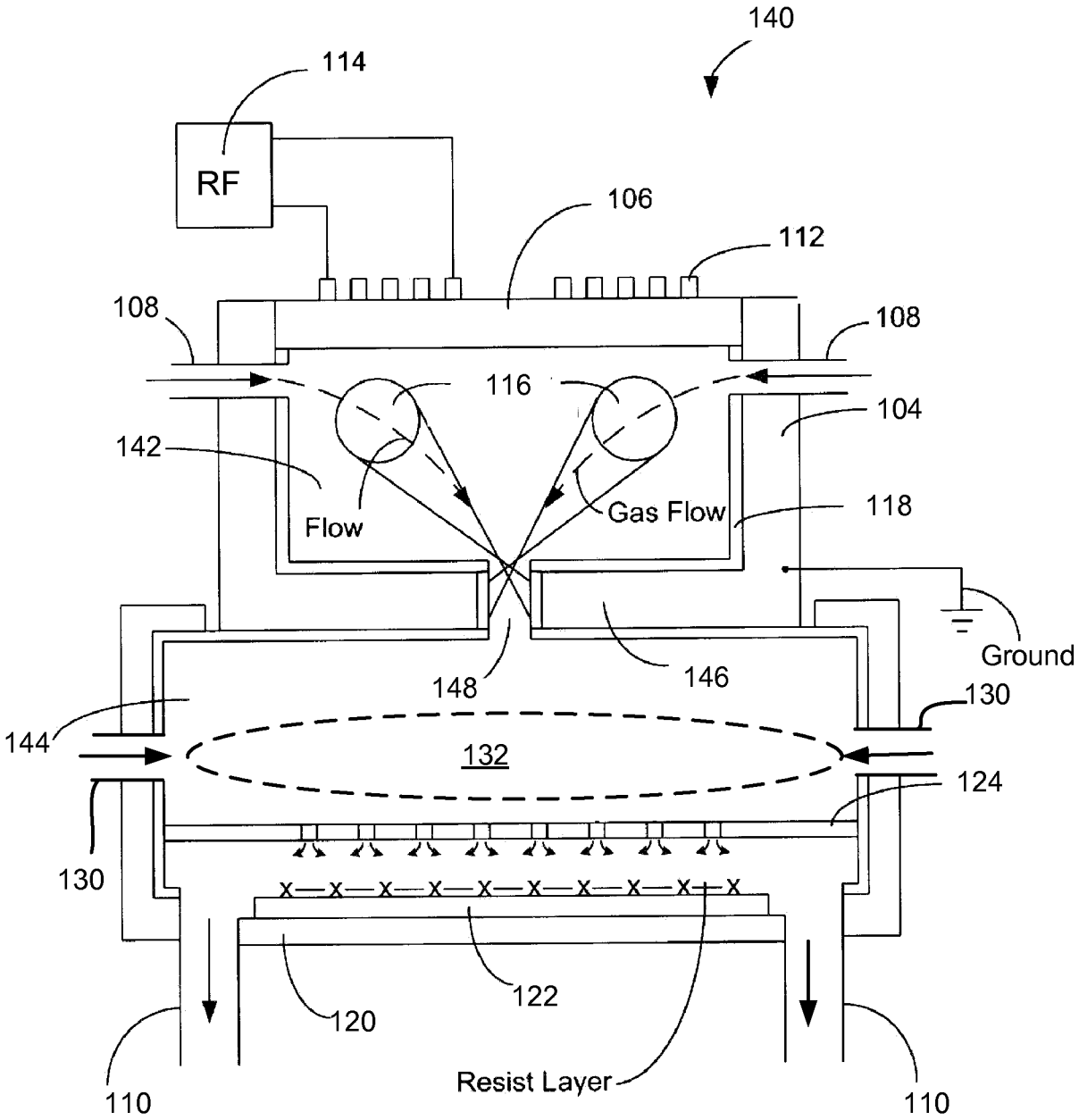

140
114
RF
106
112
108
108
116
104
142
Flow
Gas Flow
118
Ground
148
146
130
144
132
124
130
120
122
Resist Layer
110
110

FIG. 11A

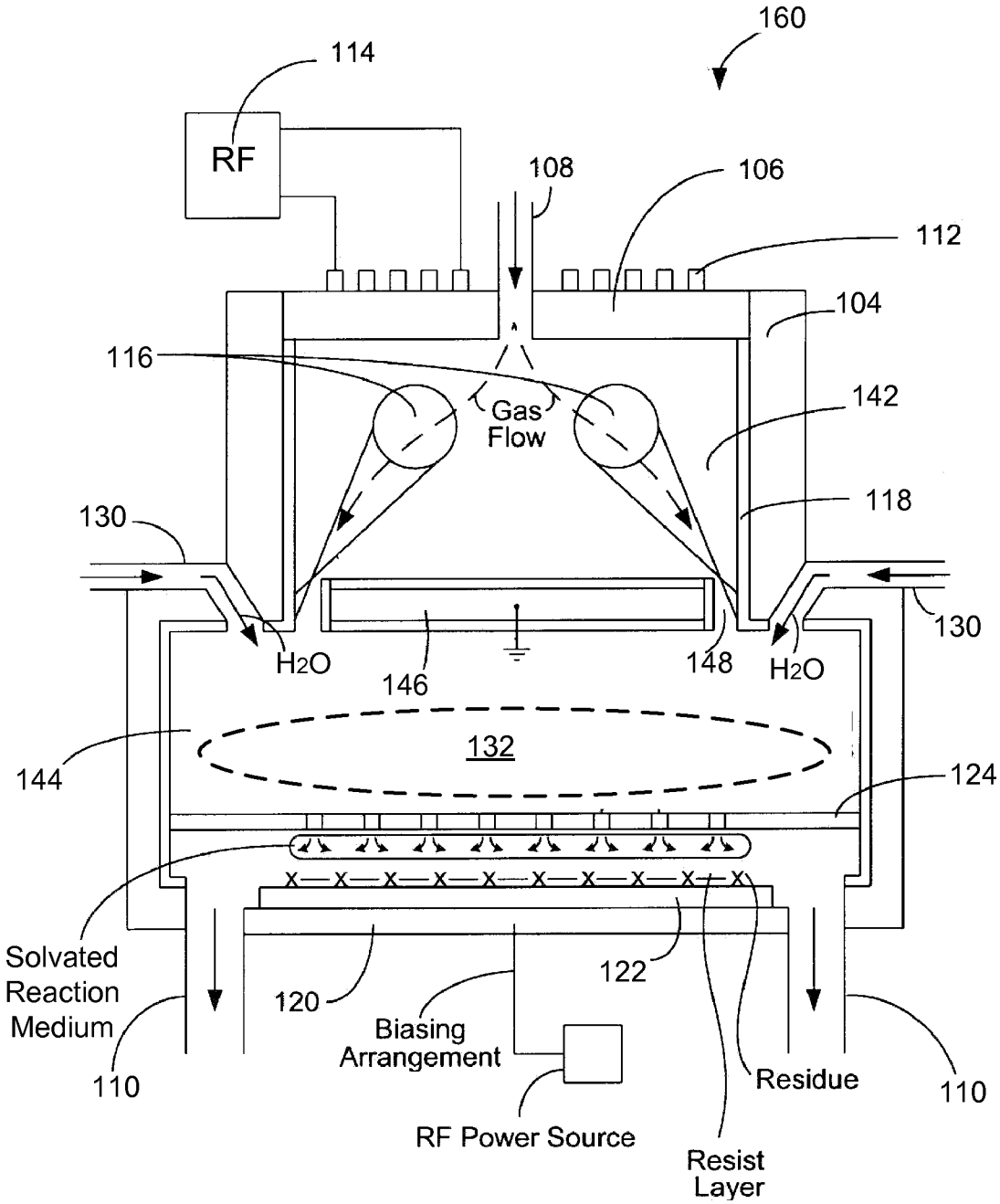

160
114
RF
108
106
112
104
116
Gas
Flow
142
118
130
130
H2O
146
148
H2O
132
144
124
Solvated
Reaction
Medium
120
122
Biasing
Arrangement
110
RF Power Source
Residue
110
Resist
Layer

FIG. 11B

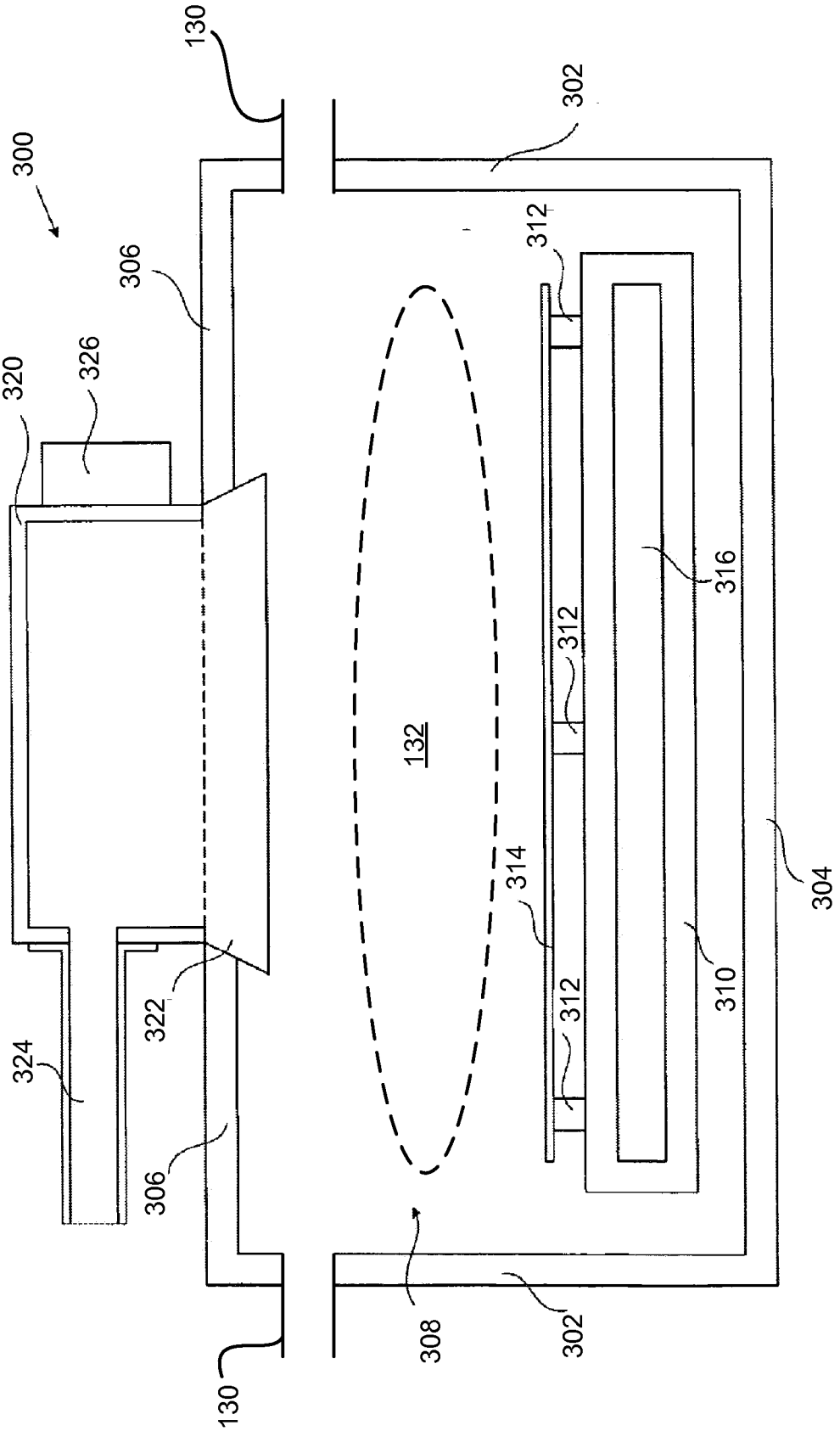

130
300
306
320
326
324
322
306
130
302
312
132
312
316
314
312
310
304
308
302

FIG. 12

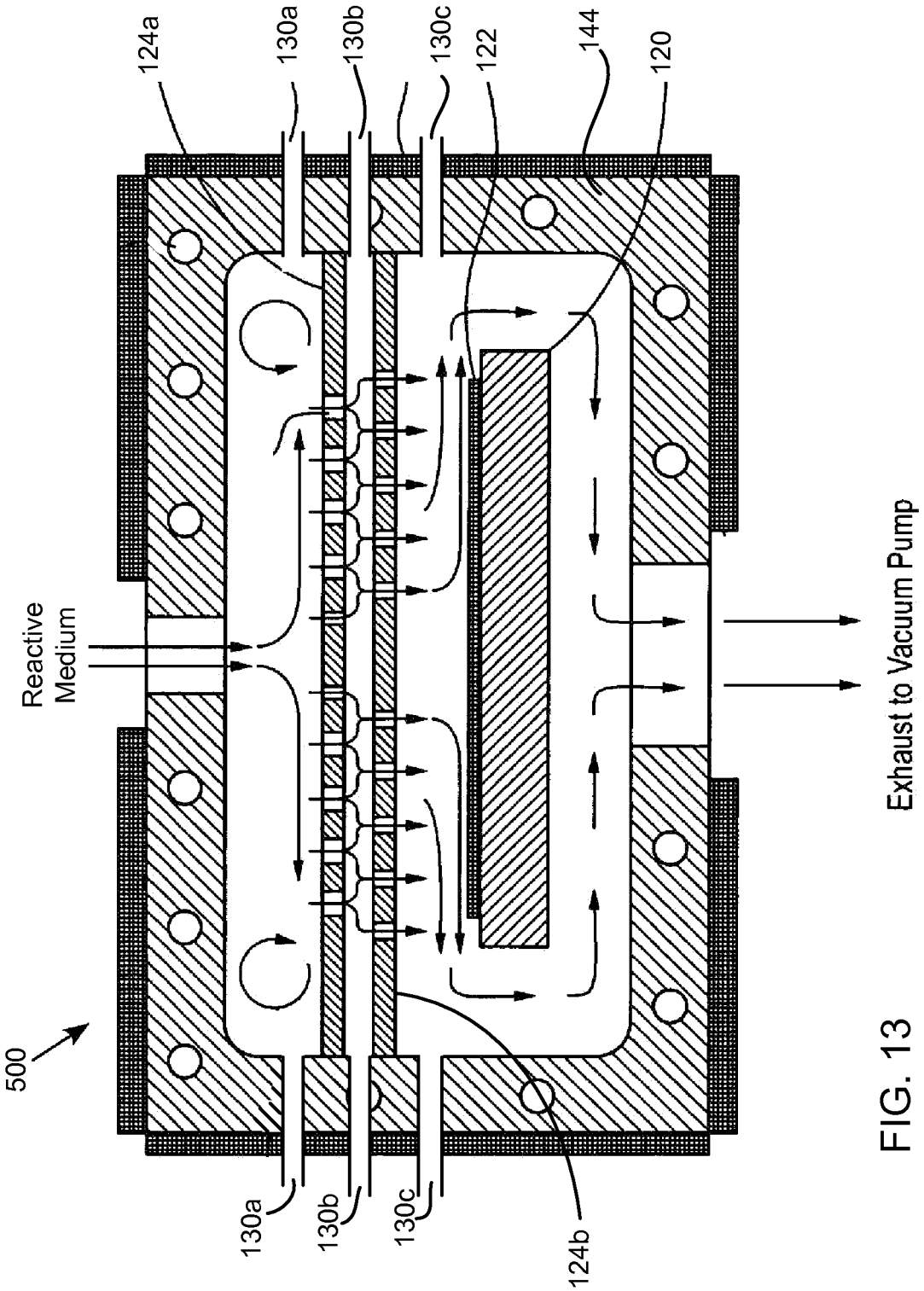

124a
130a
130b
130c
122
144
120
Reactive Medium
500
130a
130b
130c
124b
Exhaust to Vacuum Pump

FIG. 13

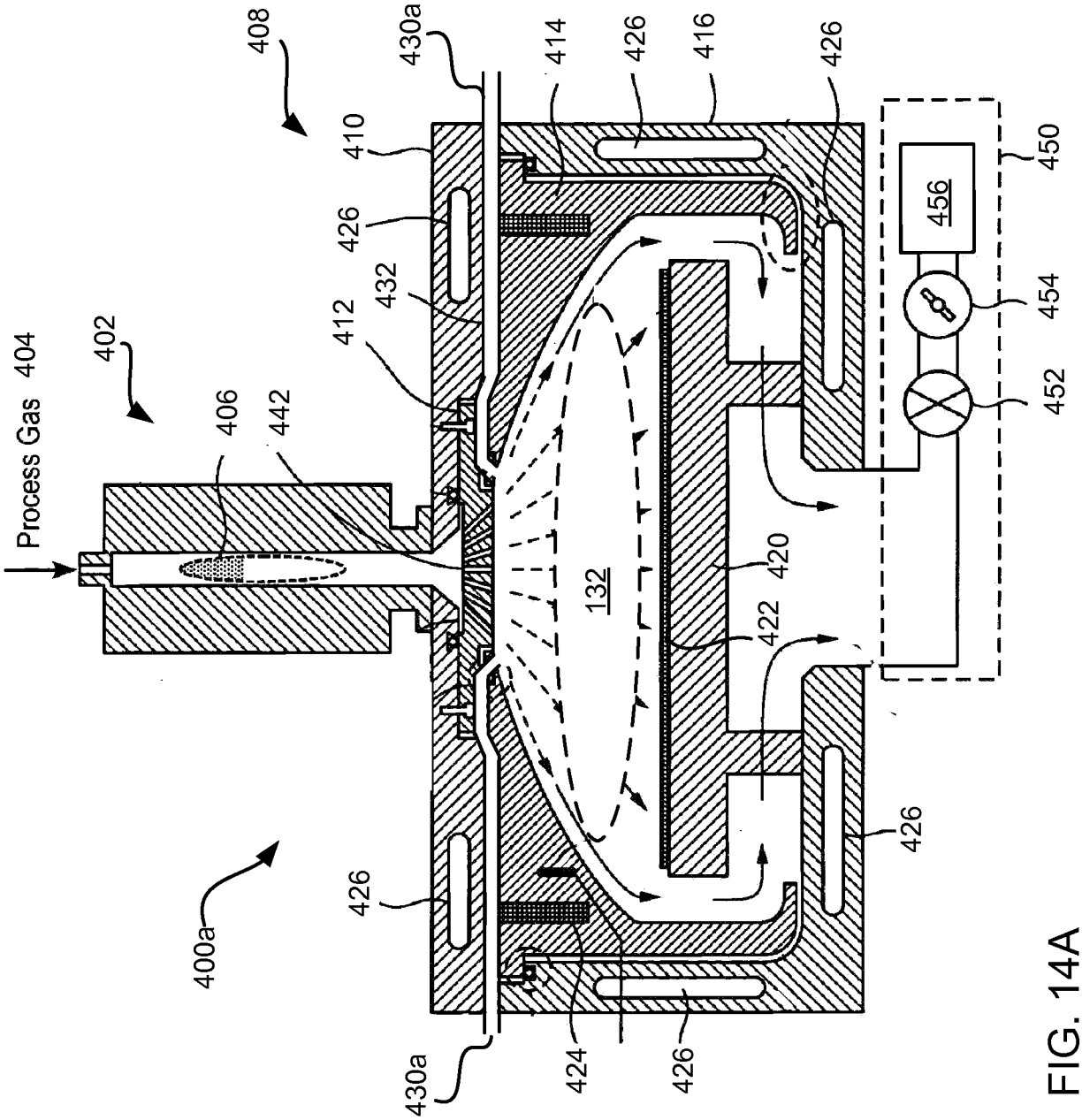

Process Gas
404
402
406
442
408
410
412
432
426
430a
414
426
416
426
450
456
454
452
420
422
132
426
426
424
426
430a
400a

FIG. 14A

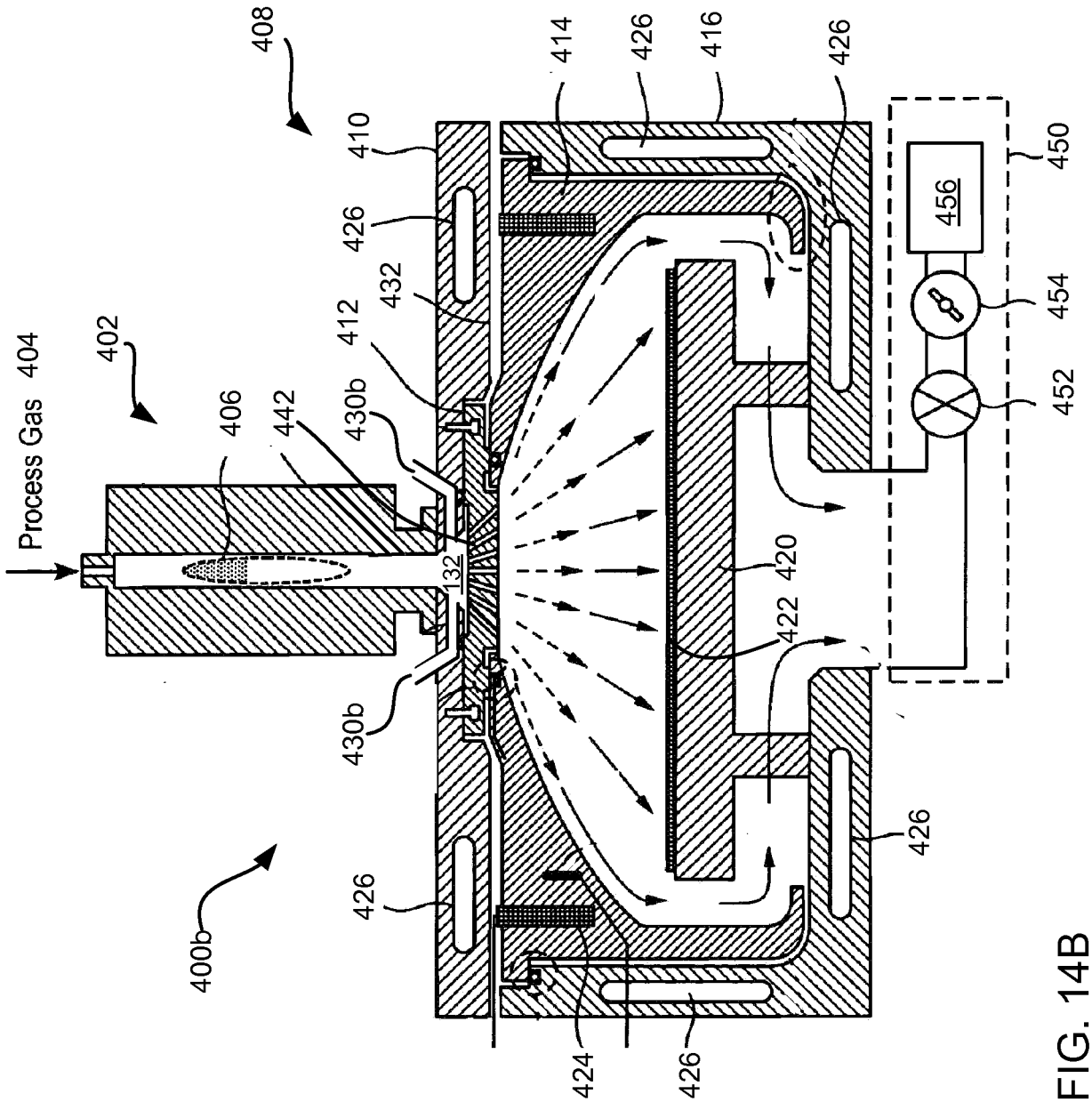

Process Gas
404
402
406
442
430b
412
432
426
410
408
414
426
416
426
450
456
454
452
420
422
132
430b
426
400b
424
426
426

FIG. 14B